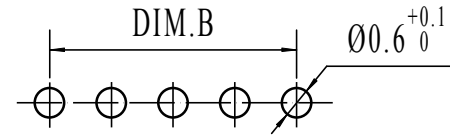
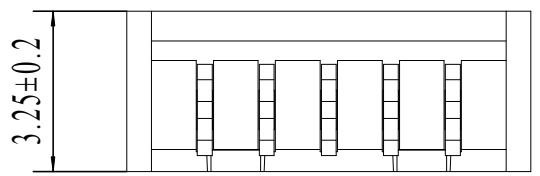
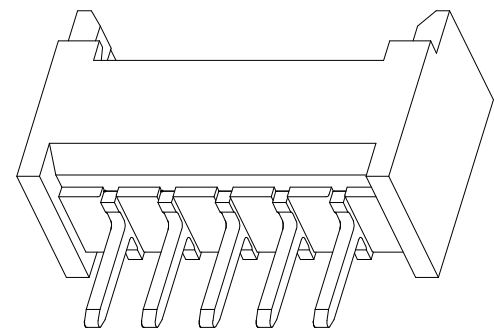
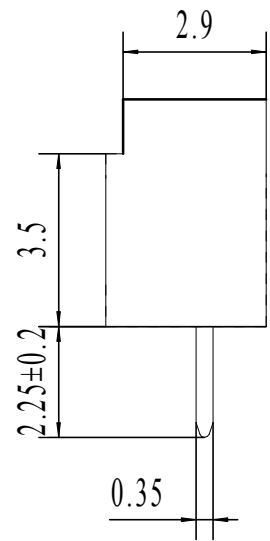
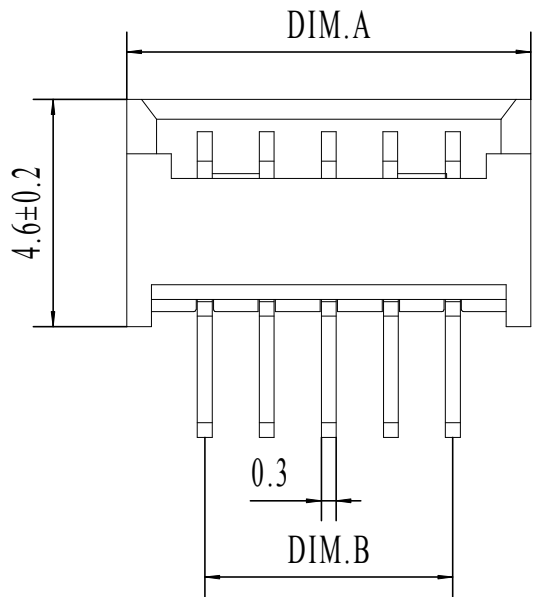


| REV. | EC# | DESCRIPTION | DATE | DRAWN | CHECK | APPROVED |
|------|-----|-------------|------------|-------|-------|----------|
| 1.00 | | 初版发行 | 2018-04-22 | | | |
| | | | | | | |



PCB LAYOUT

适应基板厚度: 1.2mm~1.6mm
 温度范围: -25°C~85°C
 额定电压: 125V AC/DC
 额定电流: 1A
 接触电阻: ≤0.02Ω
 绝缘电阻: ≥100MΩ
 耐压: 500V AC/minute

| | | |
|-----|-------|-------|
| 15 | 20.65 | 17.50 |
| 14 | 19.4 | 16.25 |
| 13 | 18.15 | 15.00 |
| 12 | 16.9 | 13.75 |
| 11 | 15.65 | 12.50 |
| 10 | 14.4 | 11.25 |
| 9 | 13.15 | 10.00 |
| 8 | 11.9 | 8.75 |
| 7 | 10.65 | 7.50 |
| 6 | 9.4 | 6.25 |
| 5 | 8.15 | 5.00 |
| 4 | 6.9 | 3.75 |
| 3 | 5.65 | 2.50 |
| 2 | 4.4 | 1.25 |
| Pin | DIM.A | DIM.B |

技术要求:

- 1) 材质: 见附表;
- 2) 电镀: 见附表;
- 3) 塑件表面平整、光洁、无毛刺、气泡、烧焦、变形、浇口无拉伤、多料或缺料等不良现象;
- 4) 端子表面无氧化、电镀不良等现象。

| GENERAL TOLERANCES | | | |
|--------------------|-------|--------|--------|
| DIM | TOL | DIM | DEG |
| X | | X° | ±3.00° |
| X.X | ±0.35 | X.X° | ±2.00° |
| X.XX | ±0.25 | X.XX° | ±1.00° |
| X.XXX | ±0.15 | X.XXX° | |

| 2 | PIN | n PCS | 材质: 黄铜, 电镀: 镀亮锡60u"MIN |
|-----|---------|-------|------------------------|
| 1 | Housing | 1 PCS | 材质: PA6T 颜色: 本色或黑色 |
| NO. | NAME | QTY | DESCRIPTION |

深圳市虹成电子有限公司

| | | | | | |
|----------|------------|------------------|---------------------|------------|------------|
| DRAW: | 2018-04-22 | TITLE: | 1.25LDIP CONN WAFER | DRAW NAME: | HCZZ0566-2 |
| DESIGN: | 2018-04-22 | SERIES: | 12502 SERIES | DRAW NO. | |
| CHECK: | 2018-04-22 | P/N: | | UNIT: | SHEET: |
| APPROVED | 2018-04-22 | CUSTOMER DRAWING | REV. 1.00 | SCALE | N/A |
| | | | | mm | 1/1 |

